



Product Change Notification

110930 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 110930 - 01
Change Title: Intel® Desktop Board DH61BE, GbE LAN, Boxed and Bulk
PCN 110930-01, Product Material
CPU Socket Cover change
Reason for Revision: Remove I/O Shield change
Date of Publication: September 09, 2011

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Sep 19, 2011
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Description of Change to the Customer:

Reason for Revision: Remove I/O Shield change

The CPU socket cover will be changed to the ILM version.

Current socket with PNP cover



New socket with ILM cover



Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers.

Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

For your information only. No change to form fit or function. No change to Intel Ordering codes.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BOXDH61BEB3	915110	G14062-206	G14062-207
BLKDH61BEB3	915111	G14062-206	G14062-207
LADH61BEB3	915112	G14063-206	G14063-207

PCN Revision History:

Date of Revision:

August 12, 2011

September 9, 2011

Revision Number:

00

01

Reason:

Originally Published PCN

Remove I/O Shield change